

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
18 December 2003 (18.12.2003)

PCT

(10) International Publication Number
WO 03/105186 A2

(51) International Patent Classification⁷: **H01L**

(21) International Application Number: PCT/IB03/02712

(22) International Filing Date: 27 May 2003 (27.05.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
P.10225042.1 6 June 2002 (06.06.2002) DE

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(81) Designated States (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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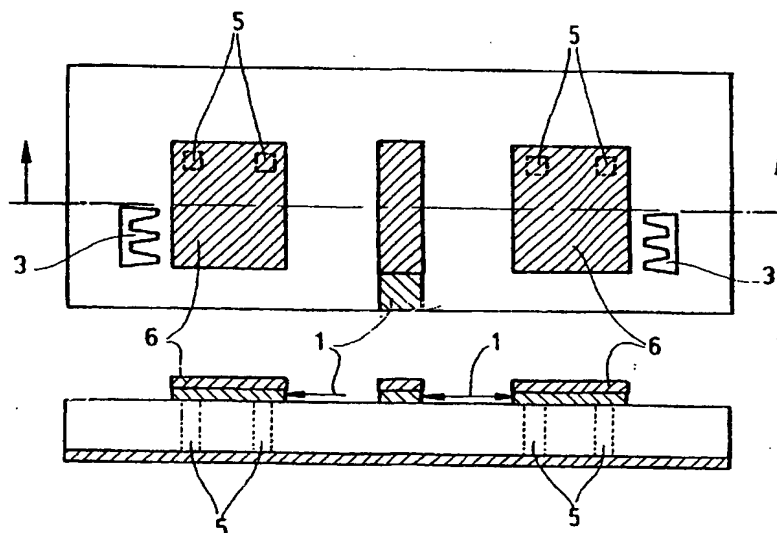
Published:

— without international search report and to be republished upon receipt of that report

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For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: INTEGRATED CIRCUIT AND METHOD FOR MANUFACTURING SAME



(57) Abstract: The invention relates to an integrated circuit having at least one microstrip line and at least one port, and to a method for manufacturing same, these being able to be used, in particular, for test passes for development purposes during chip production and also during chip manufacture. The invention provides for at least some of the ports and/or microstrip lines (1) in the integrated circuit to have a removable, reflection-free termination which is integrated on the chip. The inventive method provides for an integrated circuit to be produced in a first step, with at least some of the ports and/or microstrip lines (1) in the integrated circuit being provided with a removable, reflection-free termination which is integrated on the chip, and in a second step for this termination to be removed from a prescribable selection of the ports and/or microstrip lines (1) provided with the removable, reflection-free termination which is integrated on the chip.